MIP301

Silicon MOS IC

Features

- 100V high breakdown voltage MOS FET and CMOS control circuits are integrated into one chip
- 5V and 3 5W output with 24VDC input (Flyback method)

Applications

Drain voltage

Input voltage

Output current

Control current

Channel temperature

Storage temperature

Control voltage

● IPD for DC/DC converter

Parameter



■ Absolute Maximum Ratings (Ta = 25 ± 3°	C)
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Symbol

 V_D

V_C

VIN

 $I_{\rm D}$

 I_C

T_{ch} T_{stg} Ratings

90

8

30

1.1

0.1

150

-55 to +150

Unit

V

V

v

A

A °C

°C

Block Diagram



	Parameter	Symbol	Conditions	min	typ	max	Unit
Control functions	Output frequency	f _{OSC}	$I_C = 2mA$	180	200	220	kHz
	Maximum duty cycle	MAXDC	$I_C = 2mA$	77	80	83	%
	Minimum duty cycle	MINDC	$I_C = 10mA$	0	3	5	%
	PWM gain	GPWM		-21	-16	-11	%/mA
	Circuit current	Is		0.8	2.5	4	mA
	Dynamic impedance	ZC	$I_C = 3mA$	10	15	25	Ω
Auto-restart	Control pin charging current	I _C	$V_{C} = 0$	-2.4	-1.9	-1.2	mA
			$V_C = 5V$	-2	-1.5	- 0.8	mA
	Auto-restart threshold voltage	V _{C(on)}		5	5.7	6.3	V
	Lockout threshold voltage	V _{C(off)}		4	4.7	5.3	V
	Auto-restart hysteresis voltage	$\Delta V_{\rm C}$		0.5	1	1.5	V
Circuit protection	Self-protection current limit	I _{LIMIT}		0.9	1	1.1	A
	Leading edge blanking delay	ton(BLK)	$I_C = 3mA$		0.25		μs
	Current limit delay	t _{d(OCL)}	$I_C = 3mA$		0.1		μs
	Thermal shutdown temperature	T _{OTP}	$I_C = 3mA$	130	140	150	°C
	Power-up reset threshold voltage	V _{C reset}		2.3	3.3	4.2	V
Output	ON-state resistance	R _{DS(on)}	$I_D = 1A$		1.8	2.2	Ω
	OFF-state current	I _{DSS}	$V_{DS} = 82V$ Output MOS FET disabled		0.01	0.25	mA
	Breakdown voltage	V _{DSS}	$I_D = 0.25$ mA Output MOS FET disabled	92			V
	Rise time	t _r			0.1	0.2	μs
	Fall time	t _f			0.1	0.2	μs
Power supply voltage	Start threshold voltage	V _{IN(START)}		16		18.2	V
	Stop threshold voltage	V _{IN(STOP)}		10		12.2	V
	Input hysteresis voltage	$\Delta V_{\rm IN}$		5.5		7.5	V
	Shunt regulator voltage	V _C	$I_C = 3mA$	5.4	5.7	6.1	V
	Control supply/discharge current	I _{CD}	Output MOS FET disabled	0.5	0.8	1.1	mA

Electrical Characteristics ($T_C = 25 \pm 2^{\circ}C$)

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